



CYPRESS

Ordering Information

PHYSICAL LAYER DEVICES

PREFIX	DEVICE	SUFFIX	FAMILY
CY	P 15G 04 01 DX	- BG C T	QUAD HOTLINKII TRANSCEIVER
CY	P 15G 04 02 DX	- BG C T	QUAD HOTLINKII SERDES
CY	S 25G 01 01 DX	- AT C T	OC-48 SERDES
			PROCESSING
			T = SURFACE-MOUNTED DEVICES TO BE TAPE AND REELED
			TEMPERATURE RANGE
			C = 0°C TO +70°C
			I = -40°C TO +85°C
			PACKAGE
			BG= BALL GRID ARRAY
			AT =THERMALLY ENHANCED THIN QUAD PLASTIC FLATPACK (TQFP)
			DEVICE TYPE
			DX = DUPLEX OPERATION
			FUNCTIONAL VERSION OF DEVICE
			NUMBER OF SERIAL LINKS
			DATA RATE PER CHANNEL
			15G = 1.5 GBPS
			25G = 2.5 GBPS
			SONET COMPLIANCE
			P = NOT SONET COMPLIANT
			S = SONET COMPLIANT

PROGRAMMABLE SERIAL INTERFACE

PREFIX	DEVICE	SUFFIX	FAMILY
CY	P 15G 04 K100 V2	- MG C T	FREQUENCY AGILE DEVICE
CY	P 25G 01 K100 V1	- MG C T	HIGH SPEED DEVICE
CY	S 25G 01 K100 V1	- MG C T	HIGH SPEED DEVICE
			PROCESSING
			T = SURFACE-MOUNTED DEVICES TO BE TAPE AND REELED
			TEMPERATURE RANGE
			C = 0°C TO +70°C
			PACKAGE
			MG = MULTIPLE DICE PACKAGE
			PIN COUNT
			V1 = 456 BGA (35mm X 35mm)
			V2 = 456 BGA (31mm X 31mm)
			AMOUNT OF PROGRAMMABLE CPLD LOGIC
			K100 = 100K GATES
			K200 = 200K GATES
			NUMBER OF SERIAL LINKS
			DATA RATE PER CHANNEL
			15G = 1.5 GBPS
			25G = 2.5 GBPS
			SONET COMPLIANCE
			P = NOT SONET COMPLIANT
			S = SONET COMPLIANT

RAM, PROM, Dual-Port Static RAM, FIFO, Data Communications

PREFIX	DEVICE	SUFFIX	FAMILY
CY	7C128	-45 D M B	CMOS SRAM - FAST
CY	62256L	-70 S C	CMOS SRAM - SLOW
CY	7C245L	-35 P C	PROM
CY	7C09389V	-15 J C	MULTI-PORT STATIC RAM
CY	7C4292V	-25 AS C	FIFO
CY	7B991	-5 J C	COMMUNICATION or CHANNELS
C = CMOS B = BiCMOS			<p>PROCESSING B = MIL-STD-883C FOR MILITARY PRODUCT = LEVEL 2 PROCESSING FOR COMMERCIAL PRODUCT T = SURFACE-MOUNTED DEVICES TO BE TAPE AND REELED R = LEVEL 2 PROCESSING ON TAPE AND REELED DEVICES</p> <p>TEMPERATURE RANGE C = COMMERCIAL (0°C TO +70°C) I = INDUSTRIAL (-40°C TO +85°C) M = MILITARY (-55°C TO +125°C)</p> <p>PACKAGE A = THIN QUAD PLASTIC FLATPACK (TQFP) AS = SMALL THIN QUAD PLASTIC FLATPACK (STQFP) B = PLASTIC PIN GRID ARRAY (PPGA) BA = FINE PITCH BALL GRID ARRAY BB = FINE PITCH BALL GRID ARRAY BG = BALL GRID ARRAY BZ = FINE PITCH BALL GRID ARRAY D = CERAMIC DUAL IN-LINE PACKAGE (CERDIP)/BRAZED DIP E = TAPE AUTOMATED BONDING (TAB) F = FLATPACK (SOLDER-SEALED FLAT PACKAGE) G = PIN GRID ARRAY (PGA) H = WINDOWED LEADED CHIP CARRIER J = PLASTIC LEADED CHIP CARRIER (PLCC) K = CERPACK (GLASS-SEALED FLAT PACKAGE) L = LEADLESS CHIP CARRIER (LCC) N = PLASTIC QUAD FLATPACK (PQFP) P = PLASTIC DUAL IN-LINE (PDIP) Q = WINDOWED LEADLESS CHIP CARRIER (LCC) R = WINDOWED PIN GRID ARRAY (PGA) S = SOIC (GULL WING) T = WINDOWED CERPACK U = CERAMIC QUAD FLATPACK (CQFP) V = SOIC (J LEAD) W = WINDOWED CERAMIC DUAL IN-LINE PACKAGE (CERDIP) X = DICE (WAFFLE PACK) Y = CERAMIC LEADED CHIP CARRIER Z = THIN SHRUNK OUTLINE ZA = SMALL THIN SHRUNK OUTLINE ZR = REVERSE THIN SHRUNK OUTLINE</p> <p>SPEED (ns or MHz or other) L = LOW-POWER OPTION LL = SUPER-LOW POWER P = PCI INTERFACE V = 3.3V OPTION V25 = 2.5V OPTION A, B, C = REVISION LEVEL</p>

Cypress FSCM #65786

Modules

PREFIX	DEVICE	SUFFIX	
CYM	1838	H G -30 M B	
CYM	1465	L P D -85 C	
			PROCESSING B = MIL-STD-883C = STANDARD
			TEMPERATURE RANGE C = 0°C TO +70°C I = -40°C TO +85°C M = -55°C TO +125°C
			SPEED
			CONFIGURATION D = DUAL-IN-LINE F = FLAT SINGLE-IN-LINE G = PIN GRID ARRAY M = SINGLE-IN-LINE MEMORY MODULE (SIMM) N = SIMM FOR ANGLED SOCKETS S = SINGLE-IN-LINE V = VERTICAL DIP Z = ZIGZAG-IN-LINE
			TYPE H = HERMETIC P = PLASTIC
			POWER AND OTHER INFORMATION L = 2.0V DATA RETENTION GUARANTEED = 2.0V DATA RETENTION NOT GUARANTEED

VMEbus Products

PREFIX	DEVICE	SUFFIX	
VIC	068A	BCB	
			PROCESSING B = MIL-STD-883C = STANDARD
			TEMPERATURE RANGE C = 0°C TO +70°C I = -40°C TO +85°C M = -55°C TO +125°C
			PACKAGE A = THIN QUAD PLASTIC FLATPACK (TQFP) B = PLASTIC PIN GRID ARRAY (PPGA) G = PIN GRID ARRAY (PGA) N = PLASTIC QUAD FLATPACK (PQFP) U = CERAMIC QUAD FLATPACK (CQFP)
			A, B, C = REVISION LEVEL

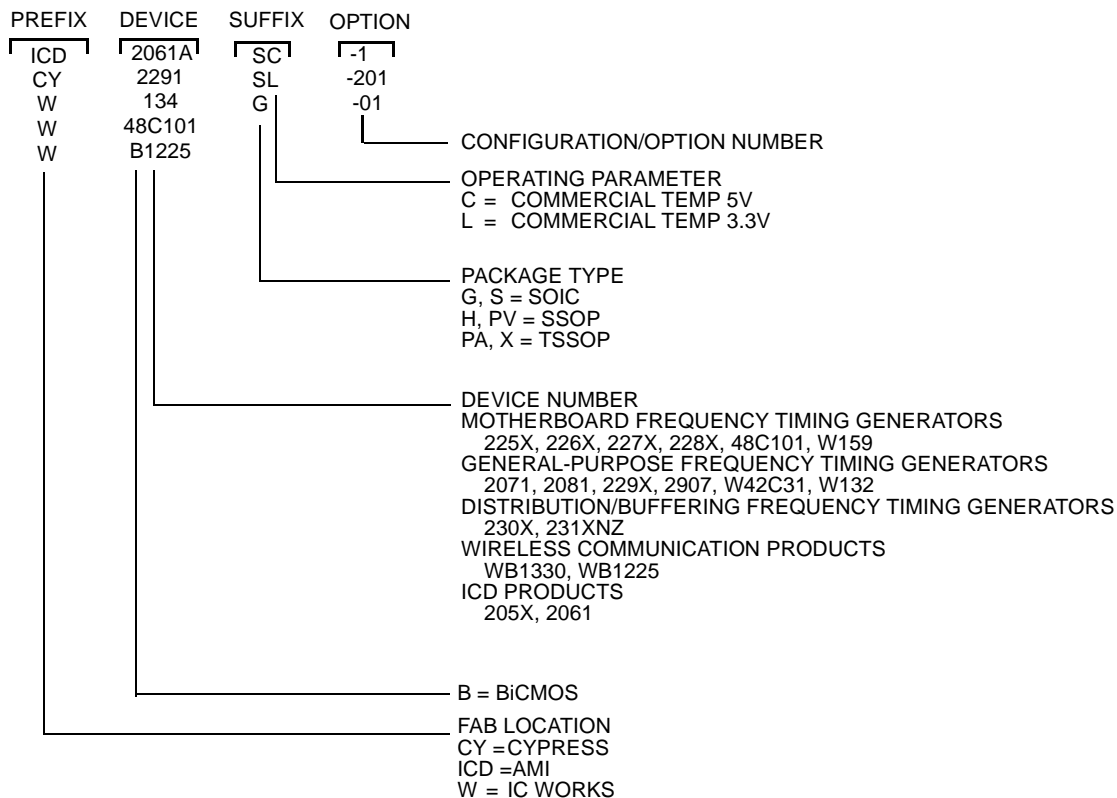
PAL & PLD

PREFIX	DEVICE	SUFFIX	FAMILY
PAL C	16R8	-25 L M B	PAL 20
PAL C	22V10	-25 W C	PAL 24 VARIABLE PRODUCT TERMS
PAL CE	16V8	-25 P C	FLASH-ERASABLE PAL20
PLD C	20G10	-25 W C	GENERIC PLD 24
CY	7C335	-83 P C	UNIVERSAL SYNCHRONOUS EPLD
CY	7C374i	-100 J C	FLASH-ERASABLE CPLD
CY	37512 V P400	-83 BB C	Ultra37000 CPLD
			PROCESSING
			B = MIL-STD-883C FOR MILITARY PRODUCT
			= LEVEL 2 PROCESSING FOR COMMERCIAL PRODUCT
			T = SURFACE-MOUNTED DEVICES TO BE TAPE AND REELED
			R = LEVEL 2 PROCESSING ON TAPE AND REELED DEVICES
			TEMPERATURE RANGE
			C = COMMERCIAL (0°C TO +70°C)
			I = INDUSTRIAL (-40°C TO +85°C)
			M = MILITARY (-55°C TO +125°C)
			PACKAGE
			A = THIN QUAD PLASTIC FLATPACK (TQFP)
			B = PLASTIC PIN GRID ARRAY (PPGA)
			D = CERAMIC DUAL IN-LINE PACKAGE (CERDIP)/BRAZED DIP
			E = TAPE AUTOMATED BONDING (TAB)
			F = FLATPACK (SOLDER-SEALED FLAT PACKAGE)
			G = PIN GRID ARRAY (PGA)
			H = WINDOWED LEADED CHIP CARRIER
			J = PLASTIC LEADED CHIP CARRIER (PLCC)
			K = CERPACK (GLASS-SEALED FLAT PACKAGE)
			L = LEADLESS CHIP CARRIER (LCC)
			N = PLASTIC QUAD FLATPACK (PQFP)
			P = PLASTIC DUAL IN-LINE (PDIP)
			Q = WINDOWED LEADLESS CHIP CARRIER (LCC)
			Q = QUARTER SIZE OUTLINE PACKAGE (for PALCE16V8 and PALCE20V8 only)
			R = WINDOWED PIN GRID ARRAY (PGA)
			S = SOIC (GULL WING)
			T = WINDOWED CERPACK
			U = CERAMIC QUAD FLATPACK (CQFP)
			V = SOIC (J LEAD)
			W = WINDOWED CERAMIC DUAL IN-LINE PACKAGE (CERDIP)
			X = DICE (WAFFLE PACK)
			Y = CERAMIC LEADED CHIP CARRIER
			BA = FINE PITCH BALL GRID ARRAY (FBGA)
			BG = BALL GRID ARRAY
			NT = THERMALLY ENHANCED PLASTIC QUAD FLAT PACK (EQFP)
			SPEED (ns or MHz)

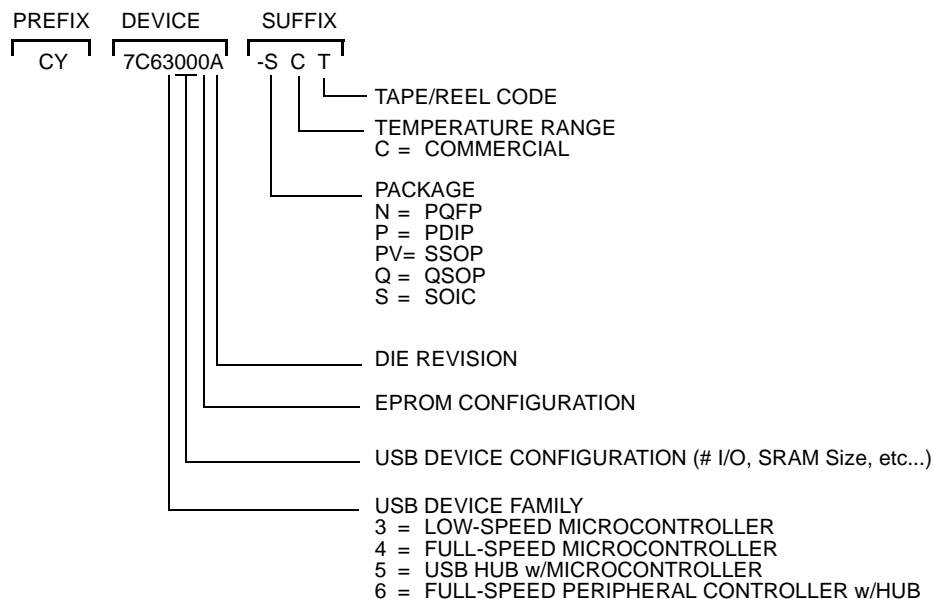
FOR 37000 ONLY:
SUPPLY VOLTAGE
V=3.3V (5V IF NOT
SPECIFIED)

FOR 37000 ONLY:
PIN COUNT (eg: P400 =
400 LEADS)

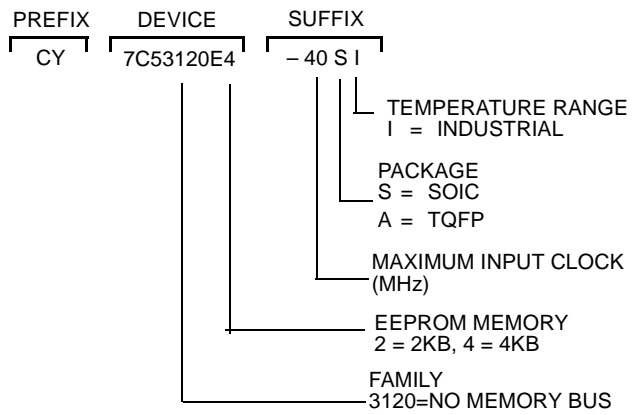
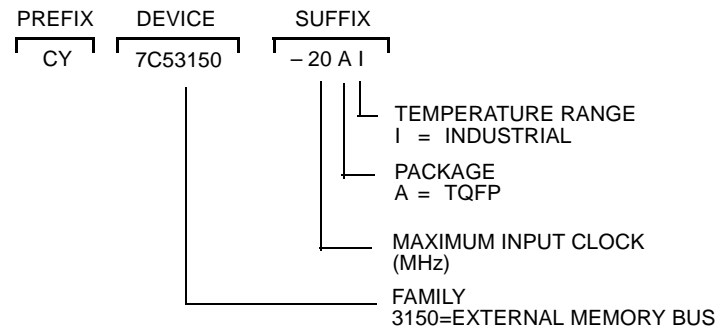
Timing Technology



USB



Neuron® Chips



PSoC Microcontroller

